

# DATA SHEET

**BYV79E series**  
Rectifier diodes  
ultrafast, rugged

Product specification

July 1998



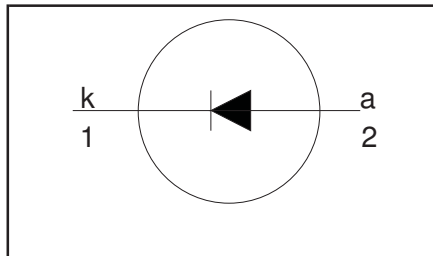
# Rectifier diodes ultrafast, rugged

## BYV79E series

### FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- Reverse surge capability
- High thermal cycling performance
- Low thermal resistance

### SYMBOL



### QUICK REFERENCE DATA

$V_R = 150 \text{ V} / 200 \text{ V}$
$V_F \leq 0.9 \text{ V}$
$I_{F(AV)} = 14 \text{ A}$
$I_{RRM} \leq 0.2 \text{ A}$
$t_r \leq 30 \text{ ns}$

### GENERAL DESCRIPTION

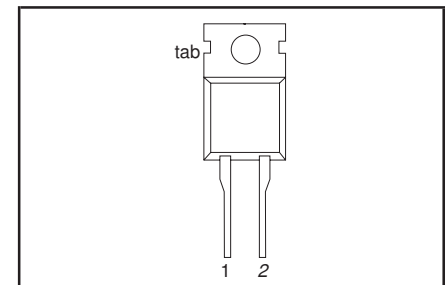
Ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV79E series is supplied in the conventional leaded SOD59 (TO220AC) package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode
tab	cathode

### SOD59 (TO220AC)



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
$V_{RRM}$	Peak repetitive reverse voltage	<b>BYV79E</b> $T_{mb} \leq 145^\circ\text{C}$	-	<b>-150</b>	<b>-200</b>	V
$V_{RWM}$	Crest working reverse voltage		-	150	200	V
$V_R$	Continuous reverse voltage		-	150	200	V
$I_{F(AV)}$	Average forward current <sup>1</sup>	square wave $\delta = 0.5; T_{mb} \leq 120^\circ\text{C}$	-	14		A
$I_{FRM}$	Repetitive peak forward current	$t = 25 \mu\text{s}; \delta = 0.5;$ $T_{mb} \leq 120^\circ\text{C}$	-	28		A
$I_{FSM}$	Non-repetitive peak forward current	$t = 10 \text{ ms}$	-	150		A
		$t = 8.3 \text{ ms}$ sinusoidal; with reappplied $V_{RWM(max)}$	-	160		A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2 \mu\text{s}; \delta = 0.001$	-	0.2		A
$I_{RSM}$	Non-repetitive peak reverse current	$t_p = 100 \mu\text{s}$	-	0.2		A
$T_{stg}$	Storage temperature		-40	150		$^\circ\text{C}$
$T_j$	Operating junction temperature		-	150		$^\circ\text{C}$

1. Neglecting switching and reverse current losses.

### ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_C$	Electrostatic discharge capacitor voltage	Human body model; $C = 250 \text{ pF}; R = 1.5 \text{ k}\Omega$	-	8	kV

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**BYV79E series****THERMAL RESISTANCES**

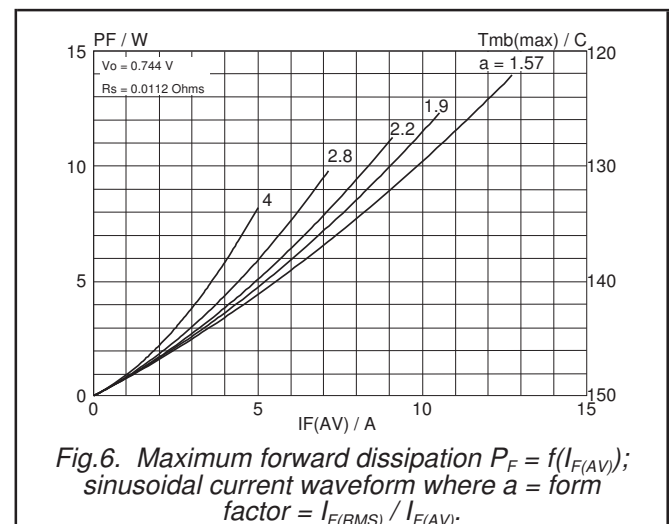
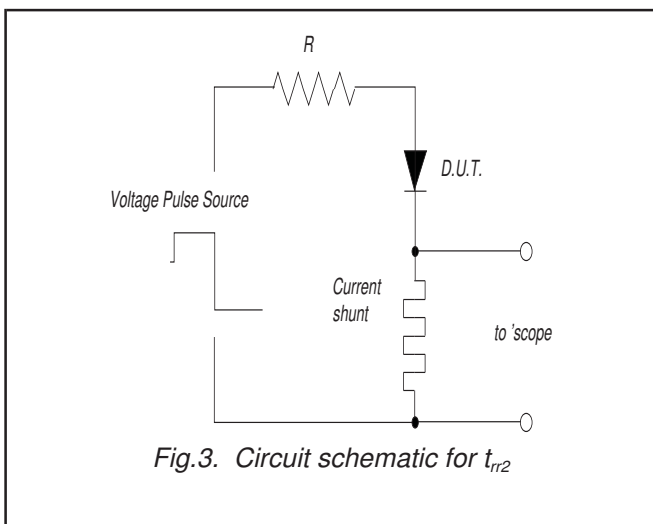
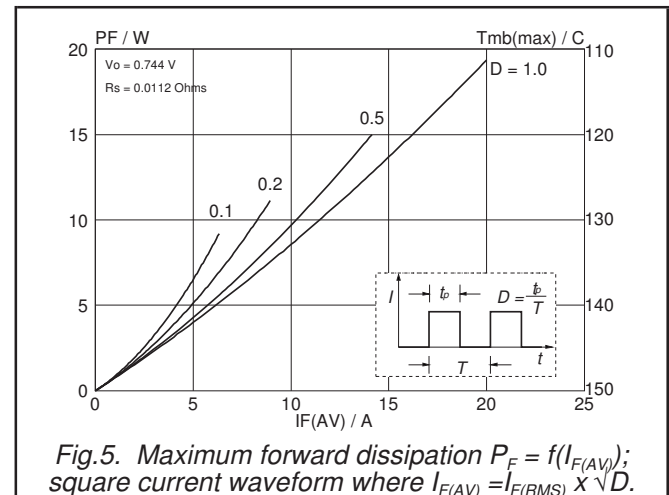
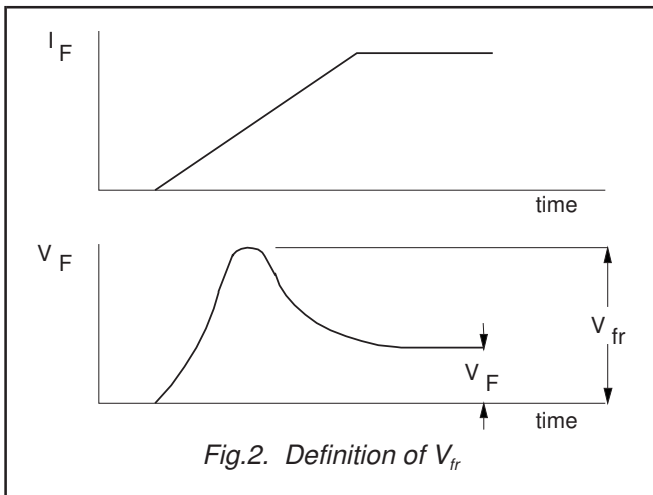
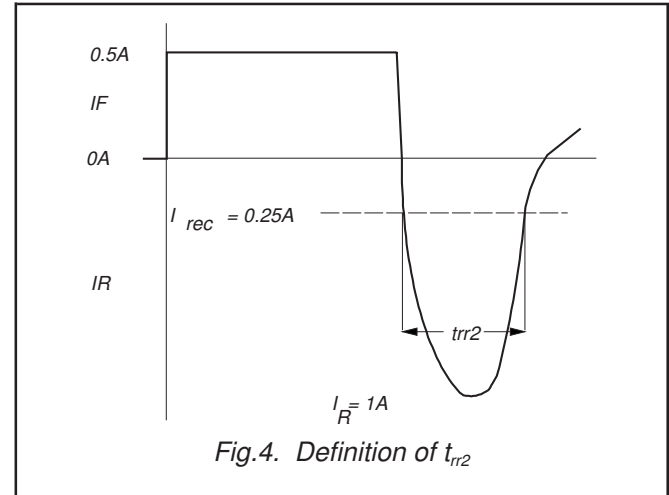
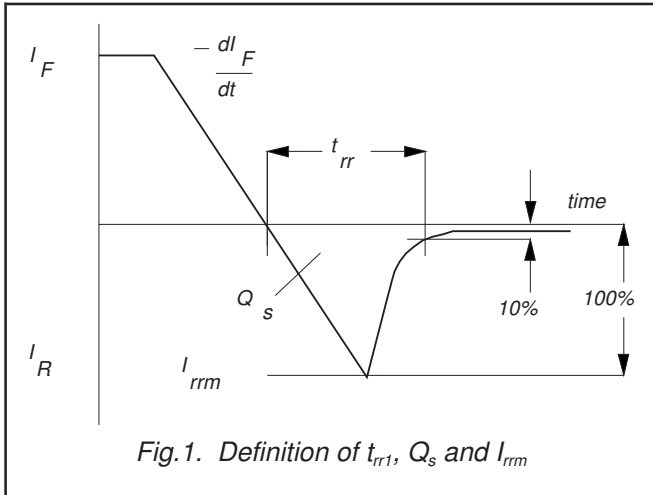
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	in free air	-	-	2	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient		-	60	-	K/W

**STATIC CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	Forward voltage	$I_F = 14\text{ A}; T_j = 150\text{ °C}$	-	0.83	0.90	V
		$I_F = 14\text{ A}$	-	0.95	1.05	V
		$I_F = 50\text{ A}$	-	1.2	1.4	V
$I_R$	Reverse current	$V_R = V_{RWM}; T_j = 100\text{ °C}$	-	0.5	1.3	mA
		$V_R = V_{RWM}$	-	5	50	$\mu\text{A}$
$Q_s$	Reverse recovery charge	$I_F = 2\text{ A}; V_R \geq 30\text{ V}; -di_F/dt = 20\text{ A}/\mu\text{s}$	-	6	15	nC
$t_{rr1}$	Reverse recovery time	$I_F = 1\text{ A}; V_R \geq 30\text{ V}; -di_F/dt = 100\text{ A}/\mu\text{s}$	-	20	30	ns
$t_{rr2}$	Reverse recovery time	$I_F = 0.5\text{ A to } I_R = 1\text{ A}; I_{rec} = 0.25\text{ A}$	-	13	22	ns
$V_{fr}$	Forward recovery voltage	$I_F = 1\text{ A}; di_F/dt = 10\text{ A}/\mu\text{s}$	-	1	-	V

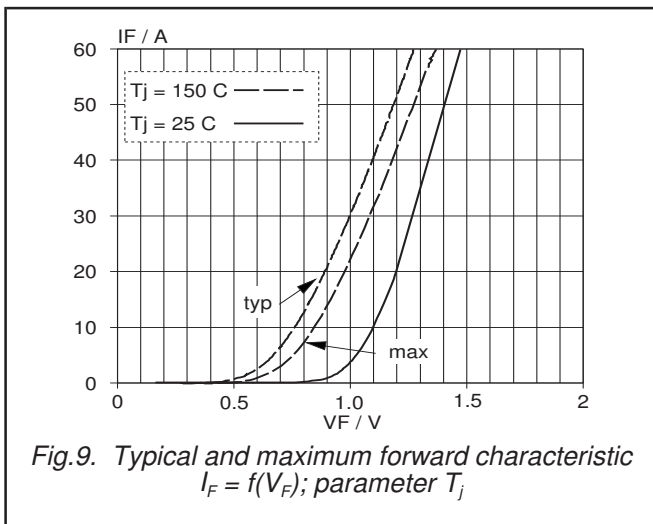
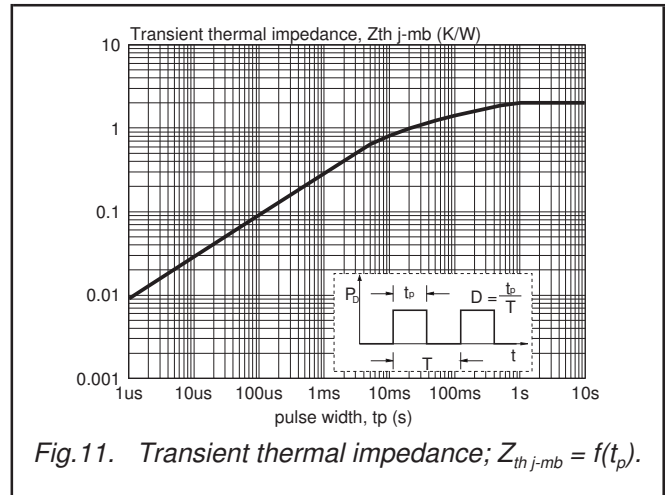
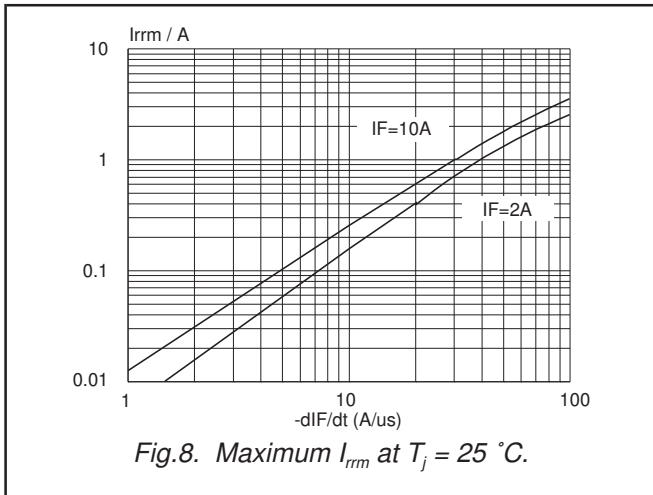
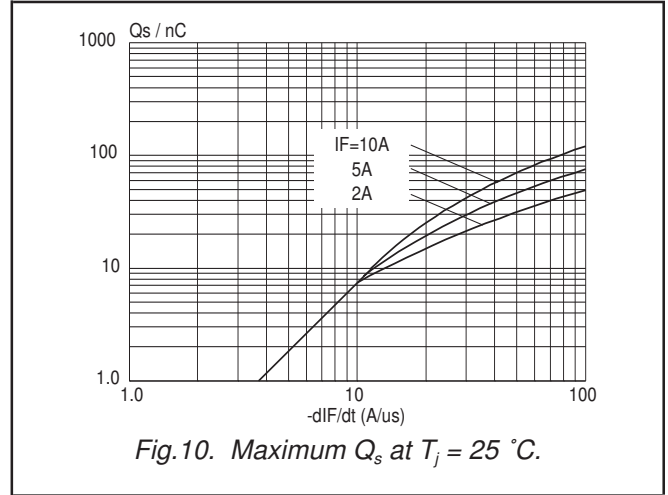
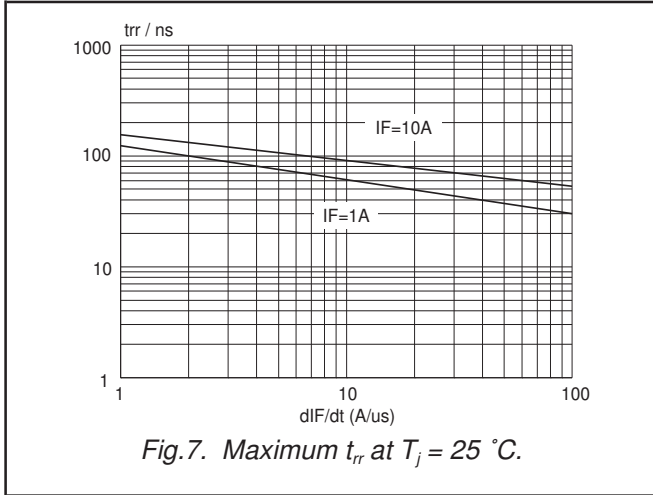
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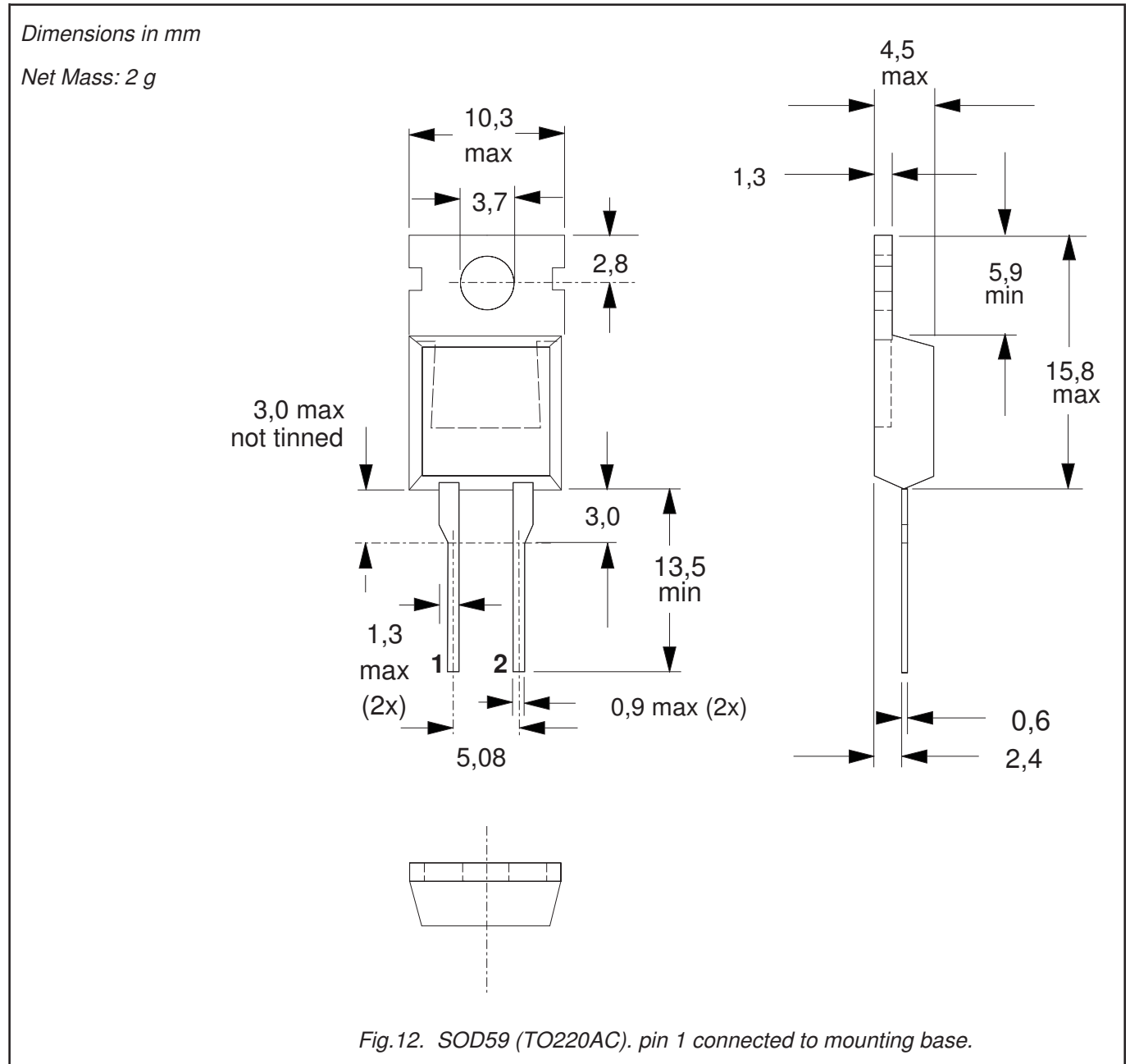
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**MECHANICAL DATA**



**Notes**

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

## Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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